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(54) **LAMINATE, RELEASE AGENT
COMPOSITION, AND METHOD FOR
MANUFACTURING PROCESSED
SEMICONDUCTOR SUBSTRATE**

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ABSTRACT

A laminate containing: a semiconductor substrate; a light-transmissive support substrate; and an adhesive layer and a release layer that are provided between the semiconductor substrate and the support substrate, wherein the release layer absorbs light emitted from a side of the support substrate and then is used for release the semiconductor substrate and the support substrate, the release layer is a layer formed of a release agent composition, and the release agent composition contains: a compound that has a structure for absorbing the light, contributes to easy release of the semiconductor substrate and the support substrate by absorbing the light, and contains at least one hydroxy group; and an organosiloxane polymer.

